

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

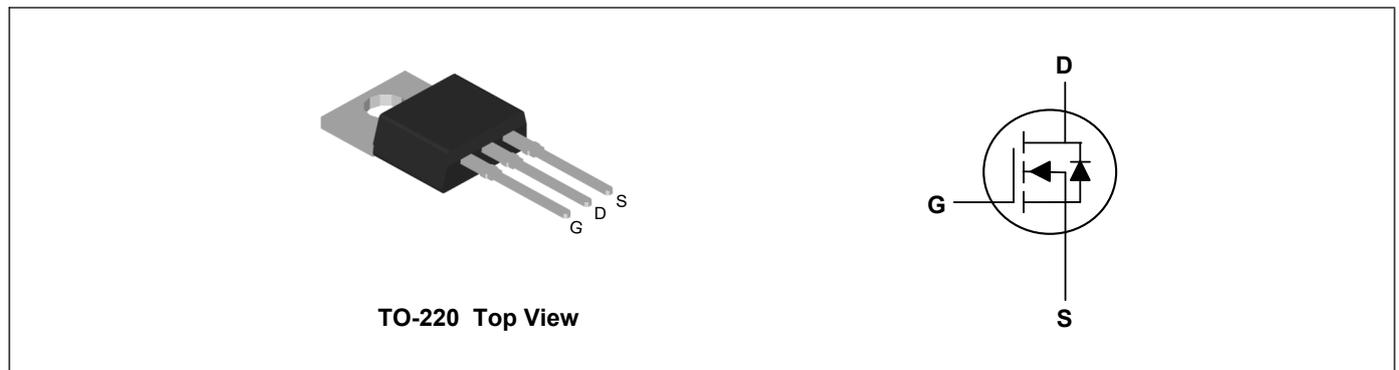
Applications

- High Frequency Point-of-Load, Synchronous Buck Converter
- Networking DC-DC Power System
- Load Switch

Product Summary



V_{DS}	60	V
I_D	120	A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	5.8	m Ω



Absolute Maximum Ratings($T_C=25^{\circ}C$, unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ¹	$I_D@T_C=25^{\circ}C$	120	A
Continuous Drain Current ¹	$I_D@T_C=100^{\circ}C$	90	A
Pulsed Drain Current ²	I_{DM}	380	A
Single Pulse Avalanche Energy ³	E_{AS}	625	mJ
Total Power Dissipation ⁴	P_D	150	W
Storage Temperature Range	T_{STG}	-55 to 150	$^{\circ}C$
Operating Junction Temperature Range	T_J	-55 to 150	$^{\circ}C$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance Junction-Case ¹	$R_{\theta JC}$	---	1	$^{\circ}C/W$

Electrical Characteristics (T_J=25°C, unless otherwise noted)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250uA	60	---	---	V
Static Drain-Source On-Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =30A	---	4.5	5.8	mΩ
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =250uA	2.0	---	4.0	V
Drain-Source Leakage Current	I _{DSS}	V _{DS} =60V, V _{GS} =0V, T _J =25°C	---	---	1	uA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
Gate Resistance	R _g	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	1.3	---	Ω
Total Gate Charge	Q _g	V _{DS} =30V, V _{GS} =10V, I _D =30A	---	72	---	nC
Gate-Source Charge	Q _{gs}		---	13	---	
Gate-Drain Charge	Q _{gd}		---	22	---	
Turn-On Delay Time	T _{d(on)}	V _{DS} =30V, V _{GS} =10V, R _G =4.5Ω, I _D =30A	---	14	---	ns
Rise Time	T _r		---	17	---	
Turn-Off Delay Time	T _{d(off)}		---	40	---	
Fall Time	T _f		---	60	---	
Input Capacitance	C _{iss}	V _{DS} =30V, V _{GS} =0V, f=1MHz	---	3000	---	pF
Output Capacitance	C _{oss}		---	430	---	
Reverse Transfer Capacitance	C _{rss}		---	240	---	

Drain-Source Diode Characteristics

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Diode Forward Voltage ²	V _{SD}	V _{GS} =0V, I _S =30A, T _J =25°C	---	0.8	1.2	V
Reverse Recovery Time	t _{rr}	I _S =30A, di/dt=100A/μs, T _J =25°C	---	50	---	nS
Reverse Recovery Charge	Q _{rr}		---	90	---	nC

Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V_{DD}=50V, L=0.5mH
- 4.The power dissipation is limited by 150°C junction temperature

Typical Characteristics

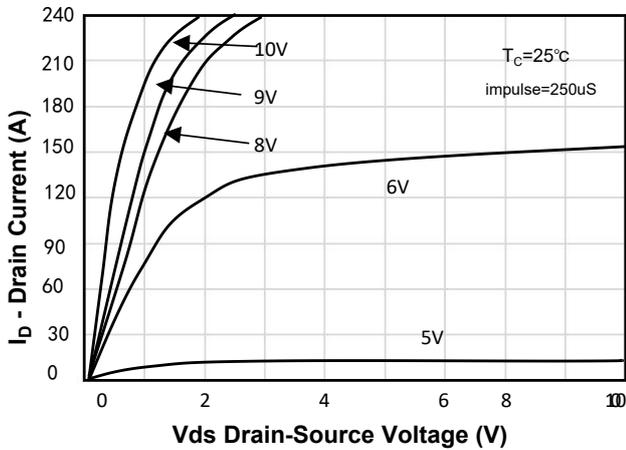


Figure 1. On-Region Characteristics

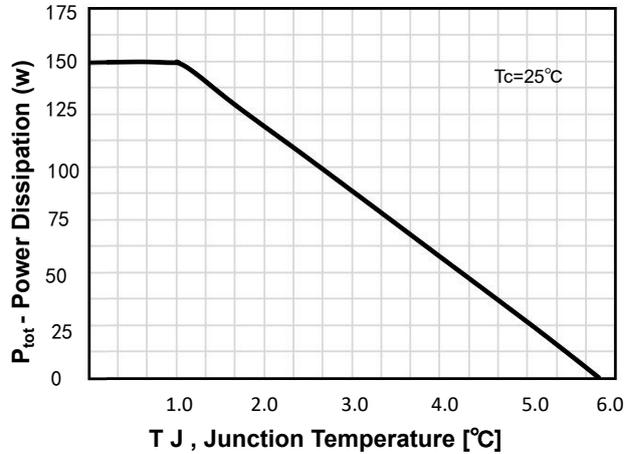


Figure 2. Power Dissipation vs Temperature

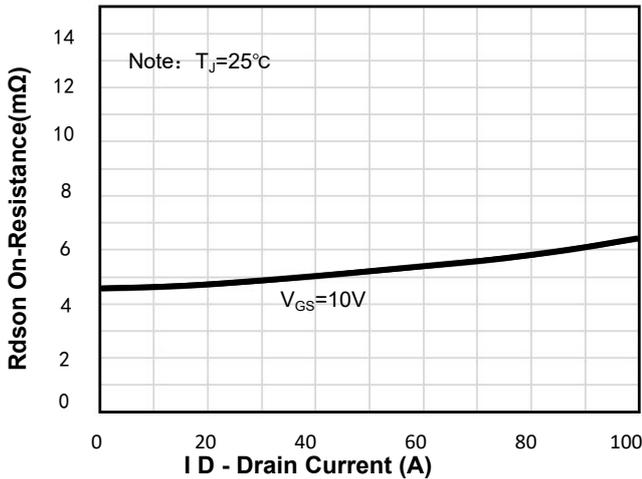


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

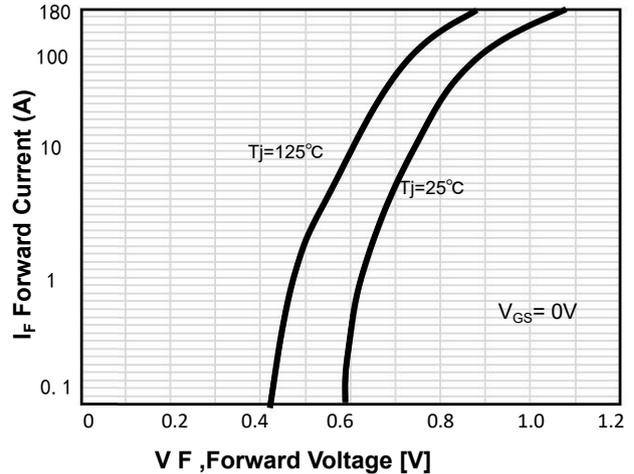


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

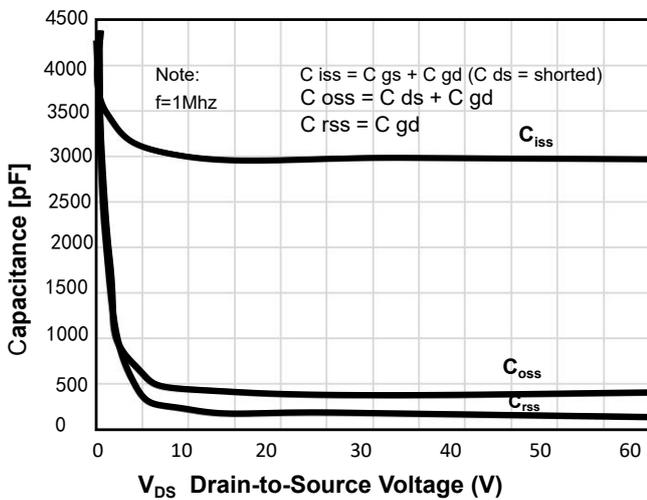


Figure 5. Capacitance Characteristics

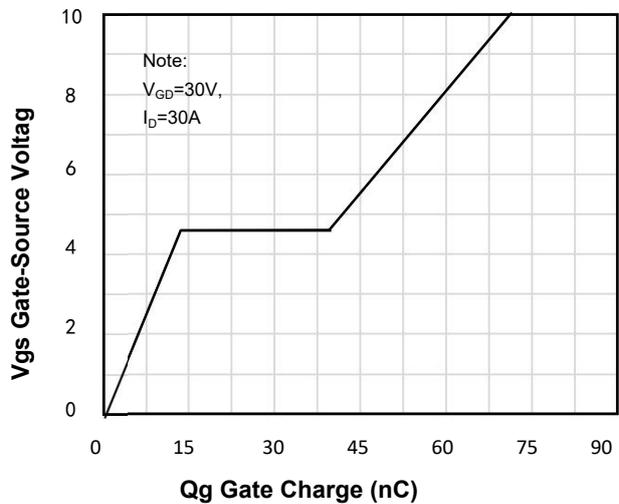


Figure 6. Gate Charge Characteristics

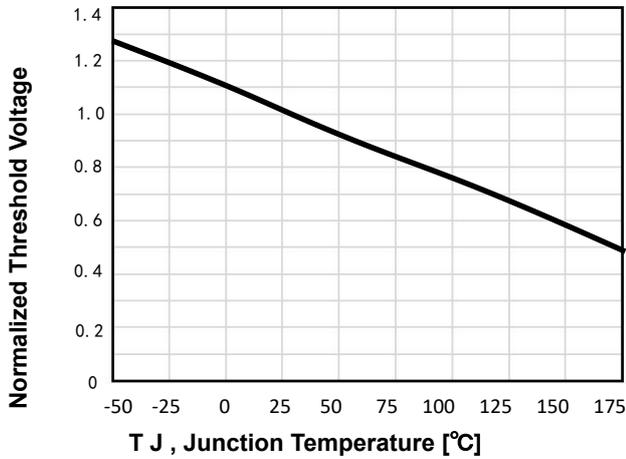


Figure 7. Normalized Threshold Voltage vs Temperature

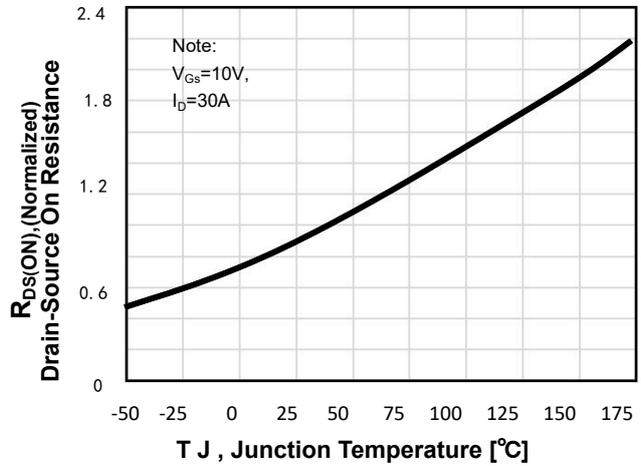


Figure 8. On-Resistance Variation vs Temperature

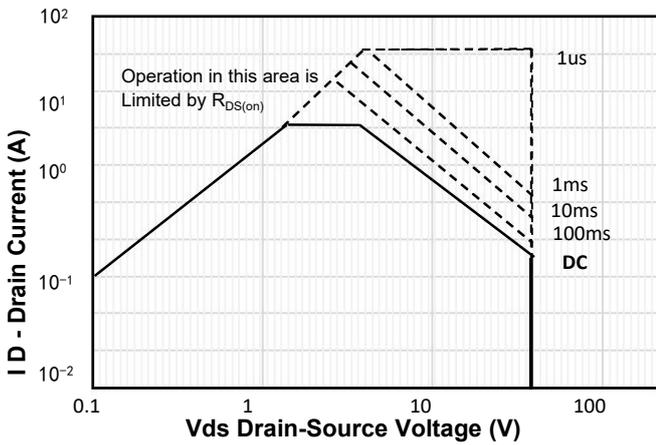


Figure 9. Maximum Safe Operating Area

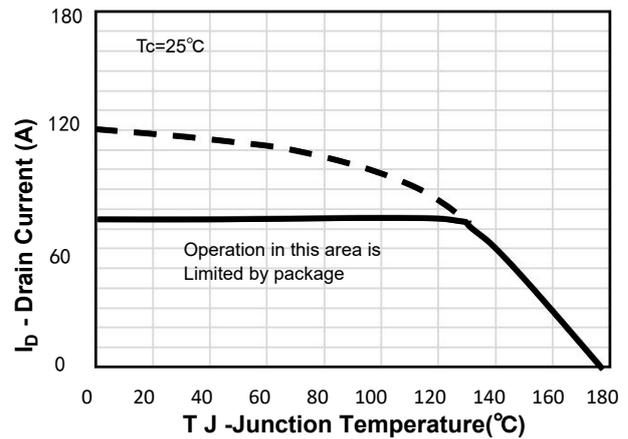


Figure 10. Maximum PContinuous Drain Current vs Case Temperature

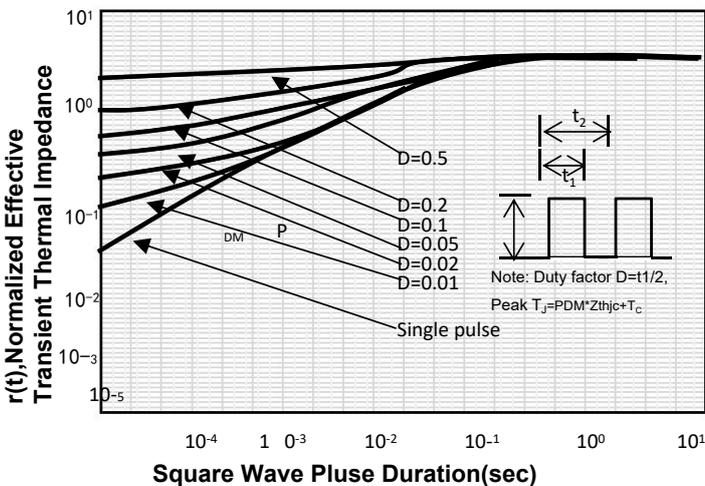
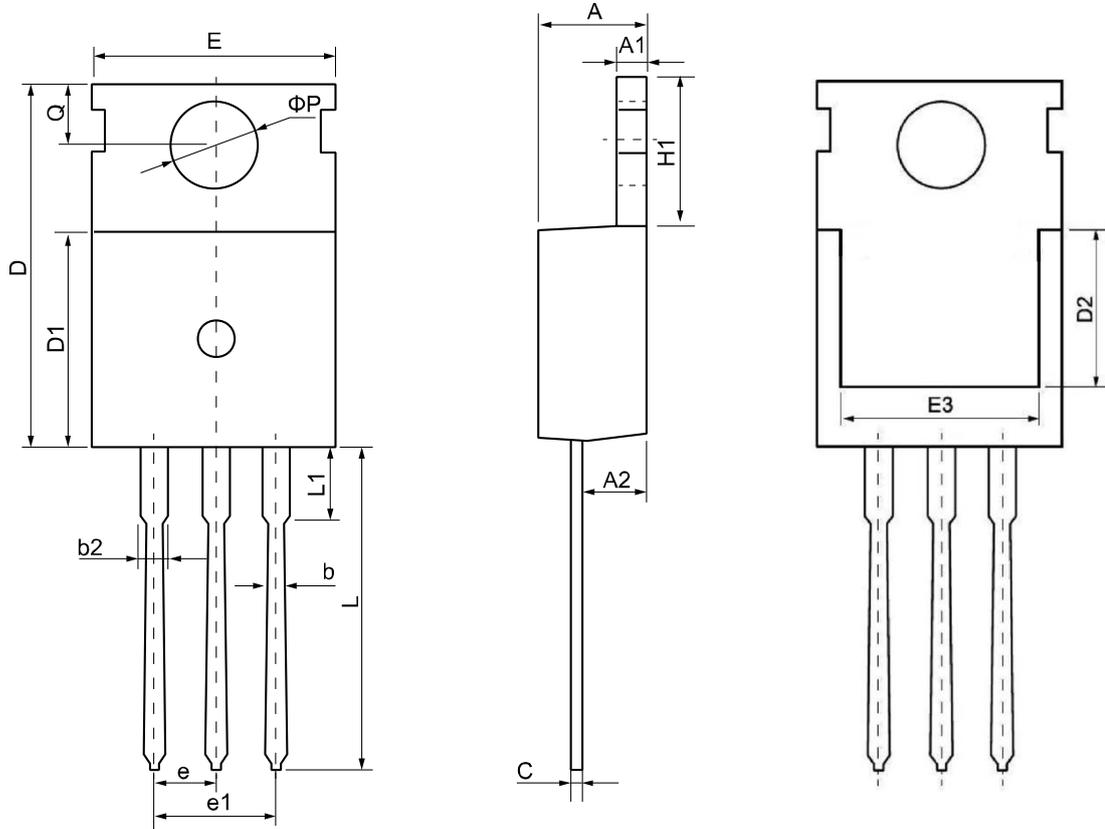


Figure 11. Transient Thermal Response Curve

TO-220 Package Outline Dimensions



Symbol	Dimensions (unit:mm)			Symbol	Dimensions (unit:mm)		
	Min	Typ	Max		Min	Typ	Max
A	4.30	4.55	4.75	E	9.65	10.00	10.25
A1	1.15	1.30	1.45	E3	7.00	--	--
A2	2.20	2.40	2.60	e	2.54 BSC		
b	0.70	0.80	0.95	e1	5.08 BSC		
b2	1.17	1.27	1.47	H1	6.30	6.50	6.80
c	0.40	0.50	0.65	L	12.70	13.50	14.10
D	15.30	15.60	15.90	L1	--	3.20	3.95
D1	8.90	9.10	9.35	phi P	3.40	3.60	3.80
D2	5.50	--	--	Q	2.60	2.80	3.00